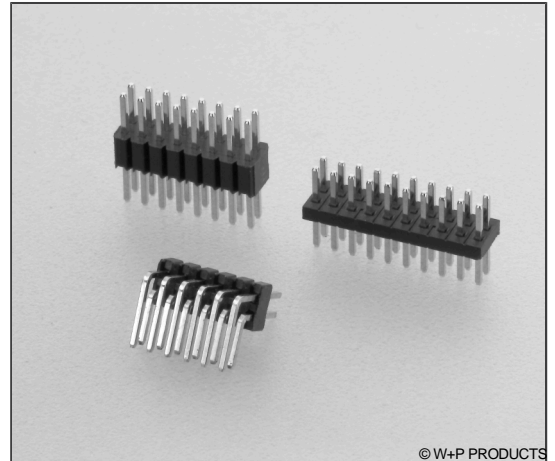


46-712 Economy Version

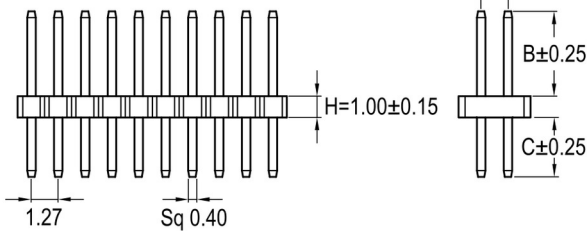
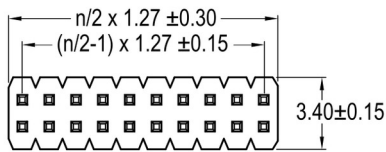
Stiftheiten RM 1,27mm, 2-reihig – 1,0 / 1,7 / 2,5mm Isolierkörper
Pin Headers, 1.27mm Pitch, Double Row – 1.0 / 1.7 / 2.5mm Insulator Body

Technische Daten / Technical Data

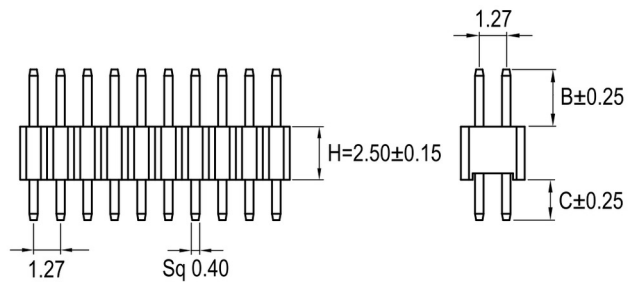
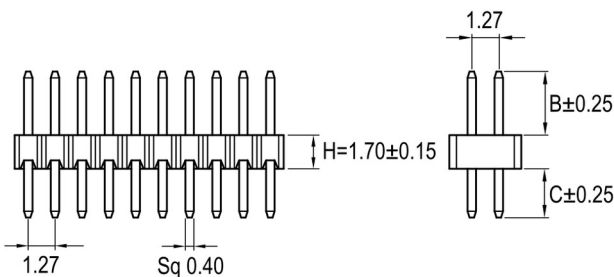
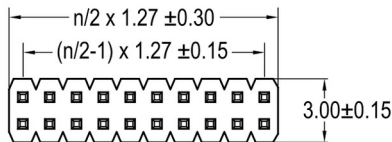
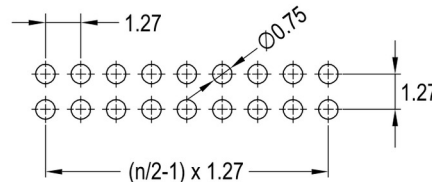
Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC/DC
Nennstrom <i>Current Rating</i>	1 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ~ +105 °C
Verarbeitung <i>Processing</i>	260 °C für 10 sec. / 230 °C für 30-60 sec. 260 °C for 10 sec. / 230 °C for 30-60 sec.



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Recommended P.C.B. Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series

46-712

Height*

1

1 H=1.00mm
2 H=1.70mm
4 H=2.50mm

Contacts*

010

004-080 H=1.0mm & 2.5mm
004-060 H=1.7

Type

1

1 Gerade
Straight

Dimensions*

10

10 B=2.7 C=2.6mm
20 B=3.0 C=3.0mm
99 Kundenspezifisch
Customer-specific

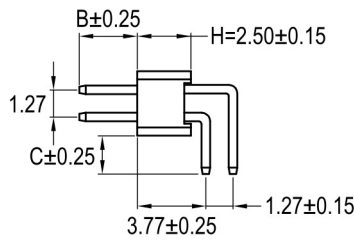
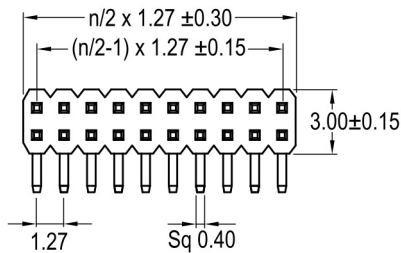
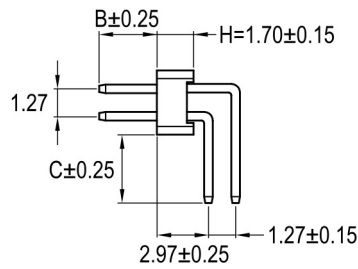
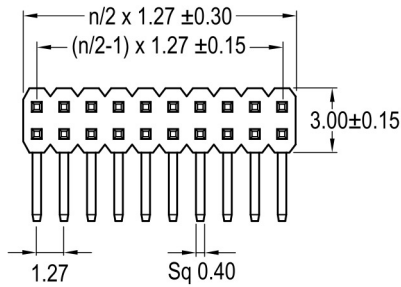
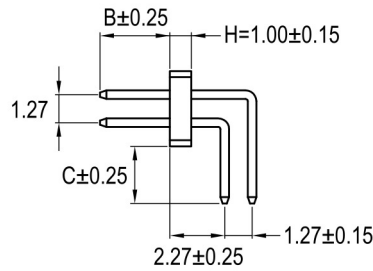
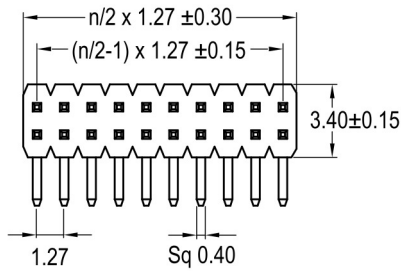
Plating

00

00 Vergoldet
Gold plated

46-712 Economy Version

Stiftleisten RM 1,27mm, 2-reihig – 1,0 / 1,7 / 2,5mm Isolierkörper
Pin Headers, 1.27mm Pitch, Double Row – 1.0 / 1.7 / 2.5mm Insulator Body



Series	Height*	Contacts*	Type	Dimensions*	Plating
46-712	1 1 H=1.00mm 2 H=1.70mm 4 H=2.50mm	020 004-080 H=1.0mm & 2.5mm 004-060 H=1.7	2 2 Gewinkelt Right-angled	10 10 B=3.05 C=2.30mm 20 B=1.91 C=2.30mm 99 Kundenspezifisch Customer-specific	00 00 Vergoldet Gold plated

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

